

SOT928-1

plastic thin quad flat package; 64 leads; body 7 x 7 x 1 mm

8 February 2016

Package information

1. Package summary

Terminal position code	Q (quad)
Package type descriptive code	TQFP64
Package type industry code	TQFP64
Package style descriptive code	TQFP (thin quad flat package)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
JEDEC package outline code	MS-026
Mounting method type	S (surface mount)
Issue date	3-1-2006

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	6.8	-	7	7.2	mm
E	package width	6.8	-	7	7.2	mm
A	seated height	[tbd]	-	1.2	1.2	mm
A ₂	package height	0.95	-	1	1.05	mm
n ₂	actual quantity of termination	-	-	64	-	



2. Package outline

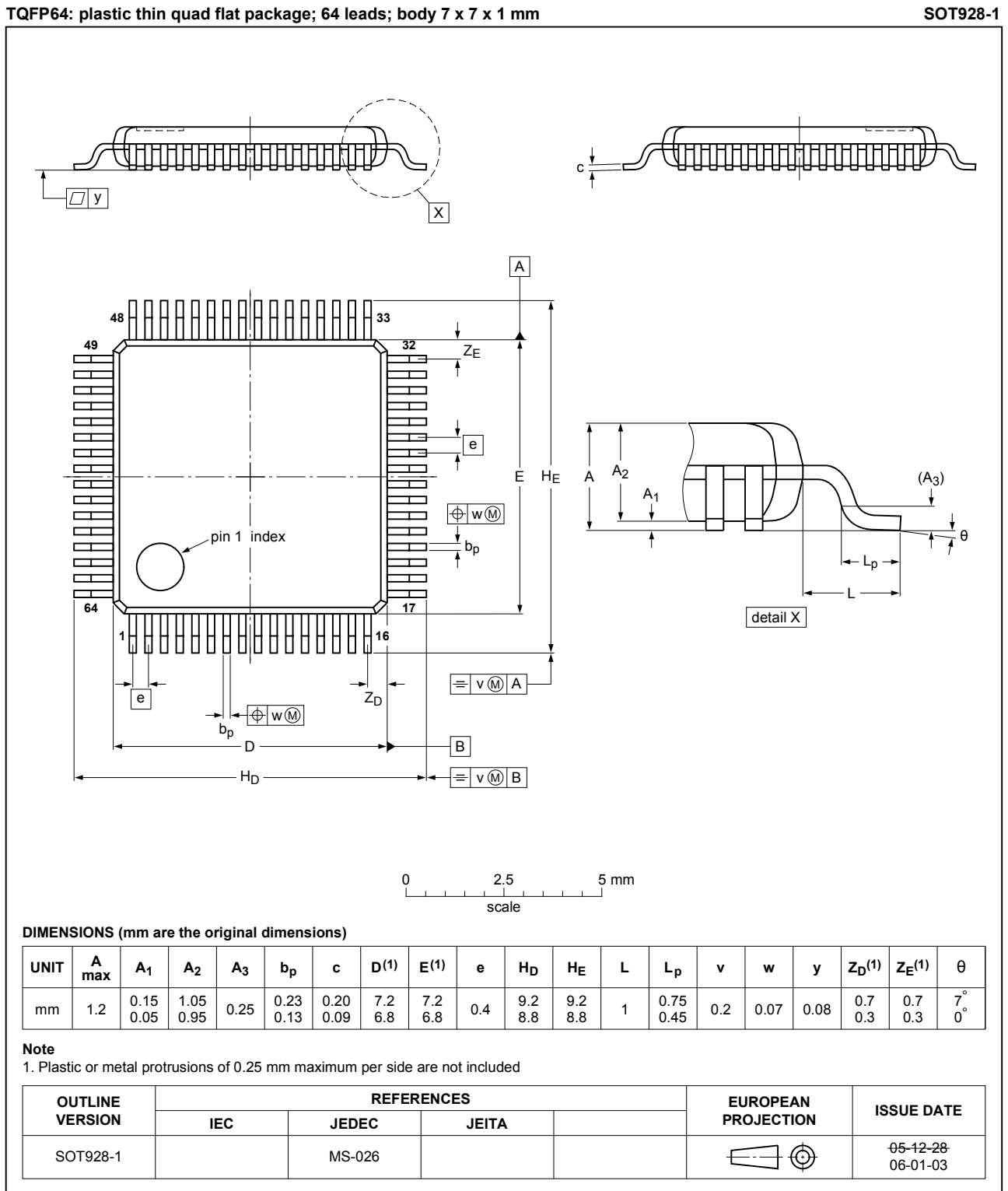


Fig. 1. Package outline TQFP64 (SOT928-1)

3. Legal information

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